

IN THE CLAIMS:

Please note that all of the claims that remain pending and under consideration in the above-referenced application are shown below. This listing of claims will replace all prior versions and listings of claims in the above-referenced application.

Please cancel claims 1-9 and 38-58 without prejudice or disclaimer.

Please enter the claims as follows:

- 1-9. (withdrawn and canceled)
10. (Currently Amended) A semiconductor device assembly comprising:
a substrate;
at least one semiconductor device secured to said substrate; and
a polymeric film separate from said substrate and positioned at least partially over at least one of said substrate and said at least one semiconductor device, said polymeric film carrying at least one conductive trace in communication with at least one of a terminal of said substrate and a bond pad of said at least one semiconductor device.
11. (original) The assembly of claim 10, wherein said polymeric film is at least partially superimposed over said at least one semiconductor device.
12. (previously amended) The assembly of claim 11, wherein said at least one conductive trace at least partially establishes communication between said bond pad of said at least one semiconductor device and a corresponding terminal of said substrate.
13. (original) The assembly of claim 12, wherein communication between said bond pad and said corresponding terminal is further established by at least one discrete conductive element positioned electrically between said at least one conductive trace and at least one of said bond pad and said corresponding terminal.

14. (original) The assembly of claim 10, comprising a plurality of semiconductor devices at different locations on said substrate.

15. (original) The assembly of claim 14, wherein said polymeric film is secured to said substrate laterally between at least two semiconductor devices of said plurality of semiconductor devices.

16. (previously amended) The assembly of claim 15, wherein at least one conductive trace carried by said polymeric film at least partially establishes communication between a bond pad of one of said at least two semiconductor devices and a corresponding bond pad of another of said at least two semiconductor devices.

17. (original) The assembly of claim 16, wherein said at least one conductive trace communicates with a terminal of said substrate which, in turn, communicates with said bond pad.

18. (original) The assembly of claim 17, further comprising discrete conductive elements between said terminal and each of said at least one conductive trace and said bond pad.

19. (original) The assembly of claim 10, wherein said substrate comprises at most four conductive layers.

20. (previously amended) The assembly of claim 10, wherein said at least one conductive trace provides a more direct electrical route than any conductive trace carried by said substrate.

21. (previously amended) The assembly of claim 16, wherein another bond pad of said at least one semiconductor device is in communication with at least a terminal of said substrate by way of another conductive trace carried by said polymeric film.

22. (original) The assembly of claim 10, wherein said polymeric film and said at least one conductive trace extend through a plane of said substrate.

23. (withdrawn) The assembly of claim 22, wherein opposite ends of said at least one conductive trace are electrically exposed at opposite sides of said polymeric film.

24. (original) The assembly of claim 22, wherein opposite ends of said at least one conductive trace are electrically exposed at the same side of said polymeric film.

25. (Currently Amended) A carrier for at least one semiconductor device, comprising:
a substrate carrying at least one terminal and at least one conductive trace; and
a polymeric film separate from said substrate, positioned at least partially over said substrate, and carrying at least one additional conductive trace.

26. (original) The carrier of claim 25, wherein said substrate comprises at most four conductive layers.

27. (original) The carrier of claim 25, wherein said polymeric film is at least partially adhered to said substrate.

28. (original) The carrier of claim 27, wherein said at least one additional conductive trace at least partially establishes communication between said at least one terminal and another terminal carried upon said substrate.

29. (previously amended) The carrier of claim 28, wherein communication between said at least one terminal and said another terminal is further established by way of at least one discrete conductive element that electrically connects said at least one additional conductive trace to at least one of said at least one terminal and said another terminal.

30. (original) The carrier of claim 25, wherein said polymeric film is configured to be disposed at least partially over the at least one semiconductor device carried by said substrate.

31. (original) The carrier of claim 25, wherein said at least one additional conductive trace carried upon said polymeric film is configured to at least partially establish communication between said at least one terminal and a corresponding bond pad of the at least one semiconductor device.

32. (original) The carrier of claim 31, wherein communication between said at least one terminal and said corresponding bond pad is further established by way of at least one discrete conductive element electrically connecting said at least one additional conductive trace to at least one of said at least one terminal and said corresponding bond pad.

33. (original) The carrier of claim 31, wherein said at least one additional conductive trace carried upon said polymeric film is configured to at least partially establish communication between a bond pad of the at least one semiconductor device and a corresponding bond pad of at least another semiconductor device carried by said substrate.

34. (original) The carrier of claim 33, wherein communication between said bond pad and said corresponding bond pad is further established by way of at least one discrete conductive element electrically connecting said at least one additional conductive trace and at least one of said bond pad and said corresponding bond pad.

35. (original) The carrier of claim 25, wherein said substrate includes at least one aperture formed therethrough for receiving a portion of said polymeric film and said at least one additional conductive trace to facilitate positioning of different portions of said polymeric film over portions of opposite sides of said substrate.

36. (withdrawn) The carrier of claim 35, wherein opposite ends of said at least one additional conductive trace are electrically exposed at opposite sides of said polymeric film.

37. (original) The carrier of claim 35, wherein opposite ends of said at least one additional conductive trace are electrically exposed at the same side of said polymeric film.

38-58. (withdrawn and canceled)

59. (Currently Amended) A semiconductor device assembly, comprising:
a substrate carrying a first plurality of conductive traces;
a routing element separate from said substrate and carrying a second plurality of conductive traces positioned at least partially on said substrate; and
at least one semiconductor device secured to said substrate.

60. (original) The assembly of claim 59, wherein said routing element is at least partially superimposed over said at least one semiconductor device.

61. (original) The assembly of claim 60, wherein at least one conductive trace of said second plurality of conductive traces at least partially establishes electrical communication between a bond pad of said at least one semiconductor device and a corresponding terminal of said substrate.

62. (original) The assembly of claim 61, wherein communication between said bond pad and said corresponding terminal is further established by at least one discrete conductive element positioned electrically between said at least one conductive trace and at least one of said bond pad and said corresponding terminal.

63. (original) The assembly of claim 59, comprising a plurality of semiconductor devices at different locations on said substrate.

64. (original) The assembly of claim 63, wherein said routing element is secured to said substrate laterally between at least two semiconductor devices of said plurality of semiconductor devices.

65. (original) The assembly of claim 64, wherein at least one conductive trace of said second plurality of conductive traces at least partially establishes communication between a bond pad of one of said at least two semiconductor devices and a corresponding bond pad of another of said at least two semiconductor devices.

66. (original) The assembly of claim 65, wherein said at least one conductive trace communicates with a terminal of said substrate which, in turn, communicates with said bond pad.

67. (original) The assembly of claim 66, further comprising discrete conductive elements between said terminal and each of said at least one conductive trace and said bond pad.

68. (original) The assembly of claim 59, wherein said substrate comprises at most four conductive layers.

69. (previously amended) The assembly of claim 59, wherein said second plurality of conductive traces of said routing element provide a more direct electrical route than any conductive trace carried by said substrate.

70. (previously amended) The assembly of claim 65, wherein another bond pad of said at least one semiconductor device is in communication with at least a terminal of said substrate by way of another conductive trace of said second plurality of conductive traces.

71. (previously amended) The assembly of claim 59, wherein said routing element and said second plurality of conductive traces extends through a plane of said substrate.

72. (previously amended) The assembly of claim 71, wherein opposite ends of at least one conductive trace of said second plurality of conductive traces are electrically exposed at opposite sides of said routing element.

73. (previously amended and withdrawn) The assembly of claim 71, wherein opposite ends of at least one conductive trace of said second plurality of conductive traces are electrically exposed at the same side of said routing element.

Please add the following new claims:

-- 74. (New) A semiconductor device assembly, comprising:
a substrate carrying a first plurality of conductive traces;
a routing element carrying a second plurality of conductive traces positioned at least partially on said substrate; and
a plurality of semiconductor devices secured to said substrate at different locations thereon.

75. (New) The assembly of claim 74, wherein said routing element is secured to said substrate laterally between at least two semiconductor devices of said plurality of semiconductor devices.

76. (New) The assembly of claim 75, wherein at least one conductive trace of said second plurality of conductive traces at least partially establishes communication between a bond pad of one of said at least two semiconductor devices and a corresponding bond pad of another of said at least two semiconductor devices.

77. (New) The assembly of claim 76, wherein said at least one conductive trace communicates with a terminal of said substrate which, in turn, communicates with said bond pad.

78. (New) The assembly of claim 77, further comprising discrete conductive elements between said terminal and each of said at least one conductive trace and said bond pad.

79. (New) The assembly of claim 76, wherein another bond pad of said at least one semiconductor device is in communication with at least a terminal of said substrate by way of another conductive trace of said second plurality of conductive traces.

80. (New) A semiconductor device assembly, comprising:
a substrate carrying a first plurality of conductive traces, said substrate comprising, at most, four conductive layers;
a routing element carrying a second plurality of conductive traces positioned at least partially on said substrate; and
at least one semiconductor device secured to said substrate.

81. (New) The assembly of claim 80, wherein said second plurality of conductive traces of said routing element provide a more direct electrical route than any conductive trace carried by said substrate.

82. (New) The assembly of claim 80, wherein said routing element and said second plurality of conductive traces extends through a plane of said substrate.

83. (New) The assembly of claim 82, wherein opposite ends of at least one conductive trace of said second plurality of conductive traces are electrically exposed at opposite sides of said routing element.--